

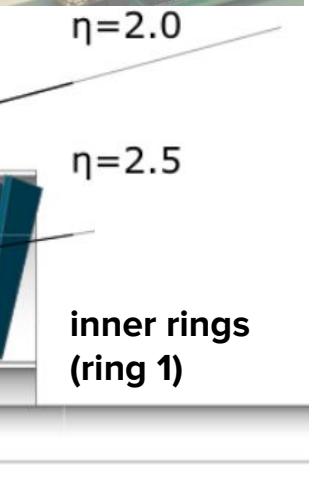
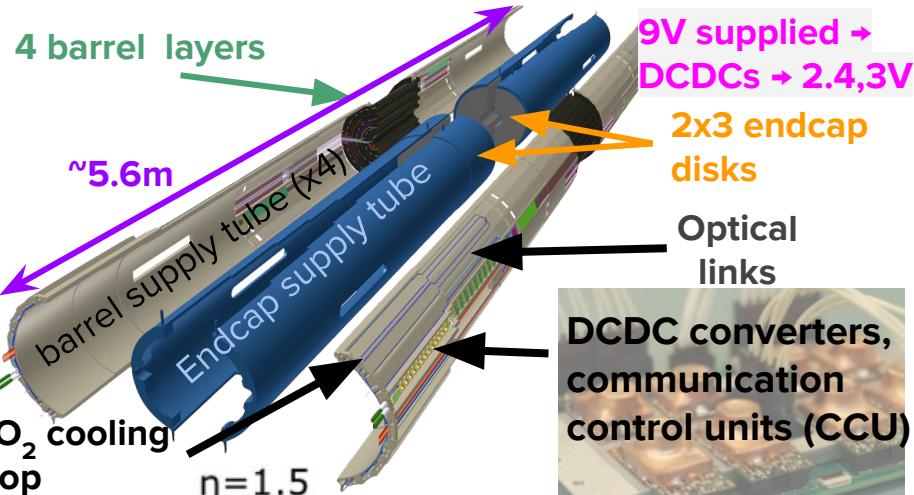
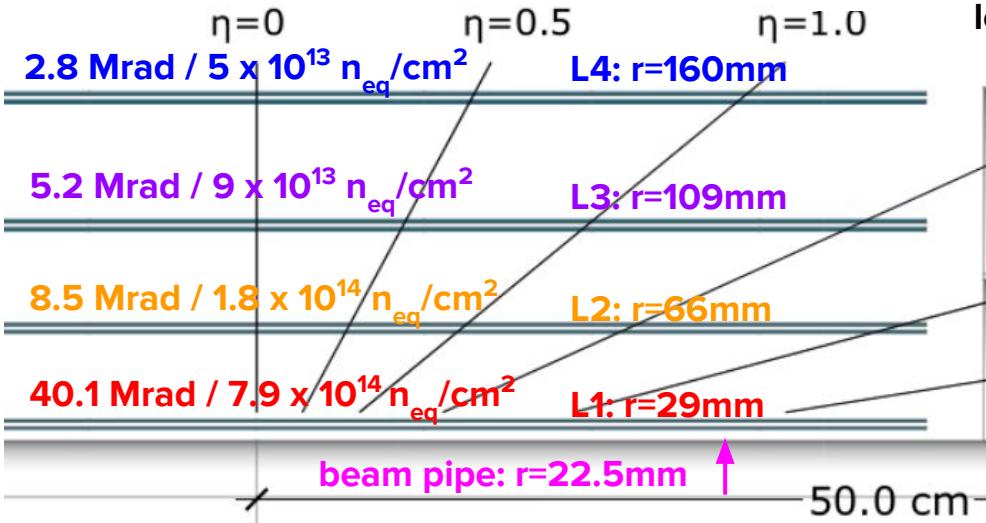
Radiation effects in the CMS phase 1 pixel detector

Jory Sonneveld on behalf of the CMS tracker group

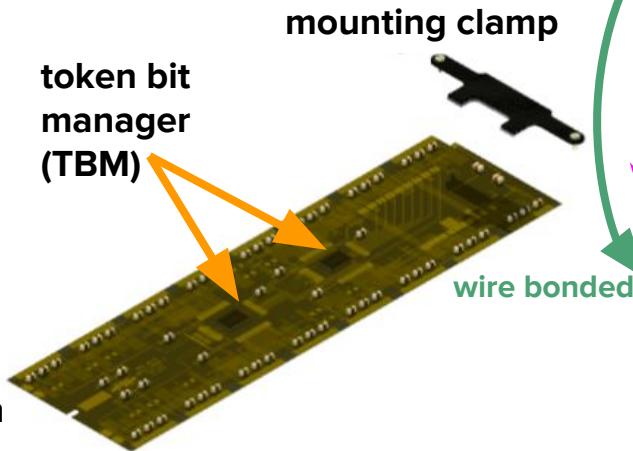
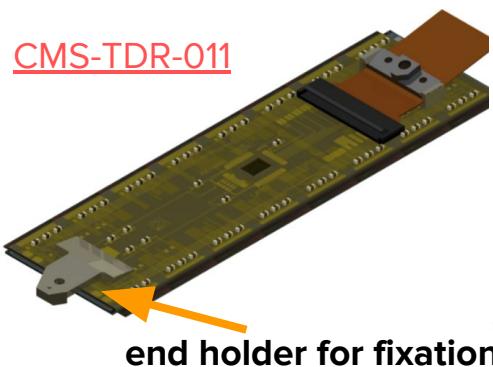
jory.sonneveld@cern.ch

CMS phase 1 pixel detector

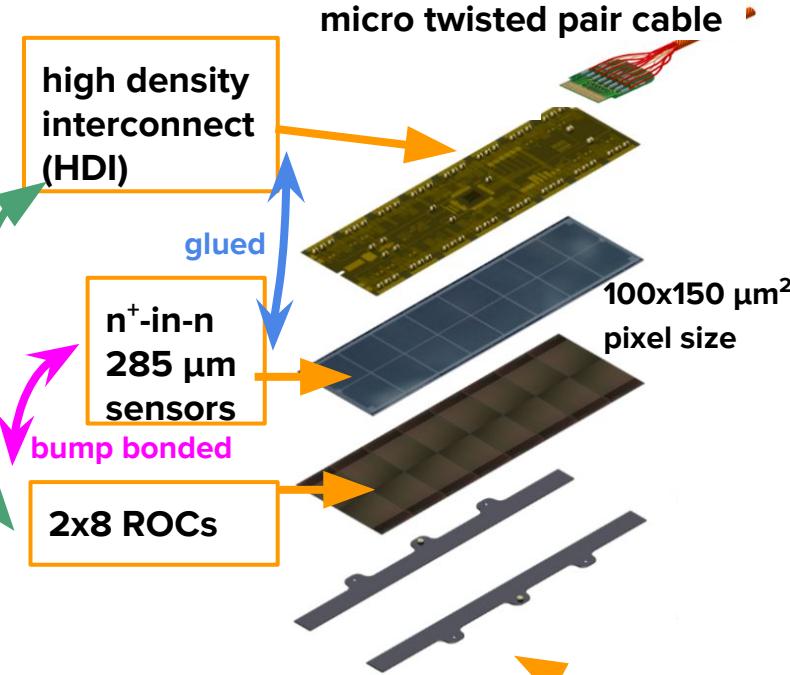
- 4 hit coverage and high-rate capability
- Turbine-like structure for endcap disks for optimal resolution
- CO_2 cooling for reduced material
- DCDC converters to keep same powering services → 9V supplied
- Uniform module design throughout



Module design



Readout chips (ROCs):
80x52pixels, 250nm CMOS
ASIC, pulse height digital
readout



Endcap disks 1-3

- 672 modules
- 40-100 MHz/cm²
- PSI46dig: column drain
- 2 TBM readout channels
- Functions up to 150 Mrad

Barrel layer 1

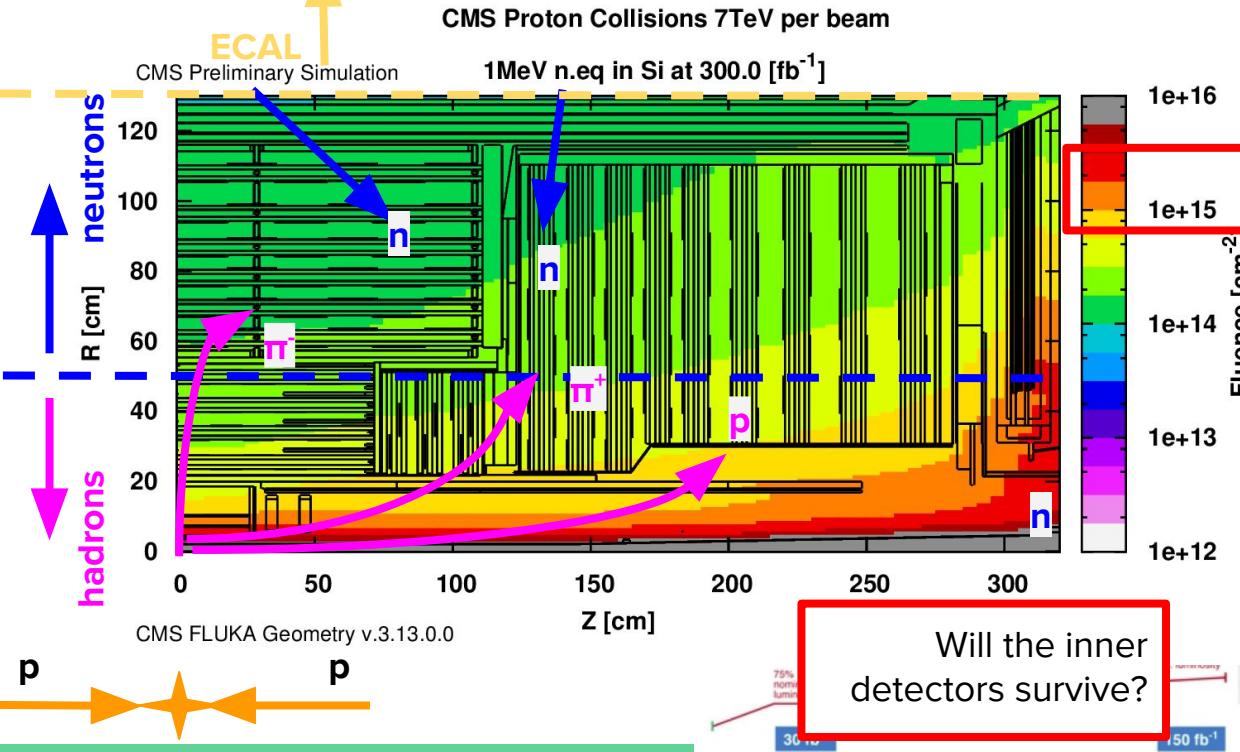
- 96 modules
- 580 MHz/cm²
- PROC600: dynamic cluster column drain
- 8 TBM readout channels
- Functions up to 480 Mrad

Barrel layer 2-4

- 1088 modules
- 40-100 MHz/cm²
- PSI46dig: column drain
- 2 TBM readout channels (L3,L4) / 4 TBM readout channels (L2)
- Functions up to 150 Mrad

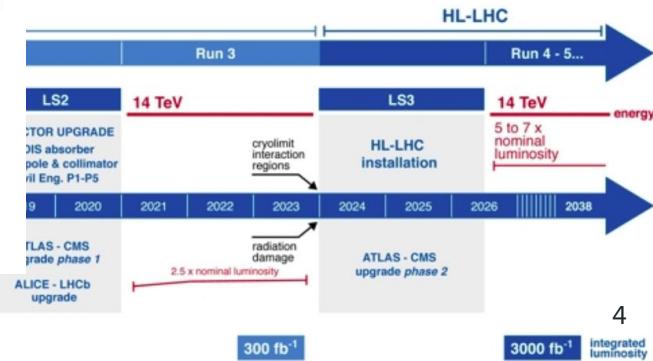
LHC: a challenging environment

2017+2018: 118 fb^{-1}
2018: 68 fb^{-1}



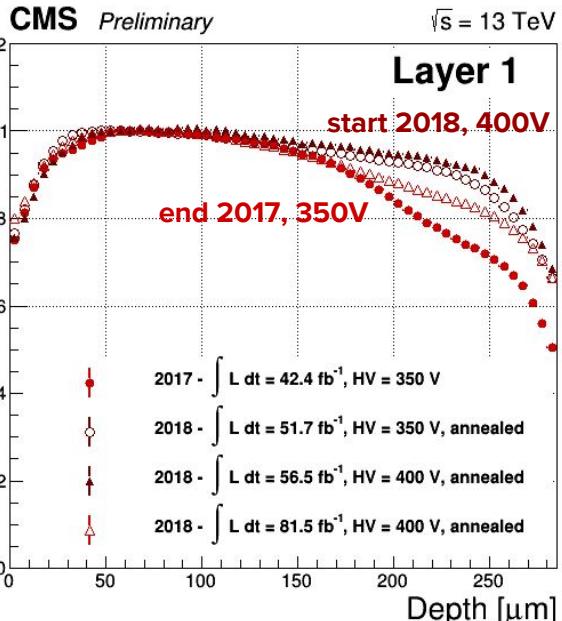
Radiation effects are challenging for operations and performance:

- Damage and single event upsets (SEUs) in electronics
 - false signals, chip damage
- Bulk defects cause change of space charge distribution
 - bias voltage increase
- Increasing leakage currents and heat dissipation
- Charge trapping in sensor:
 - decreasing charge collection efficiency



Impact on performance and data

- Radiation effects clearly seen in Lorentz angle evolution and pixel charge profile
- Effects can be reduced by increasing bias voltage and performing annealing
- Decrease in charge collection efficiency taken into account in simulation using PixelAV and TCAD.



Normalized average pixel charge vs sensor depth:

- flat for unirradiated sensors
- increase for $350 \rightarrow 400\text{V}$ and annealing
- decrease with further irradiation

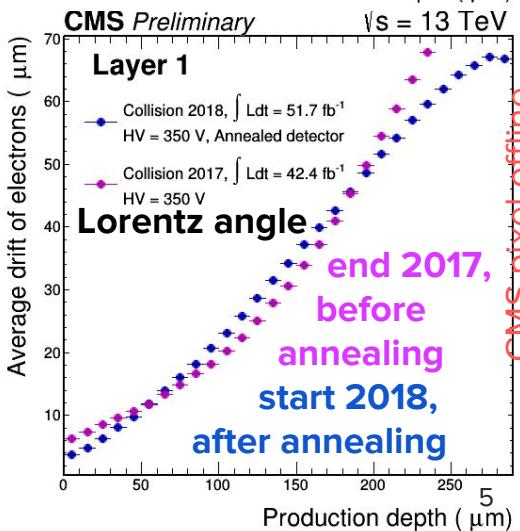
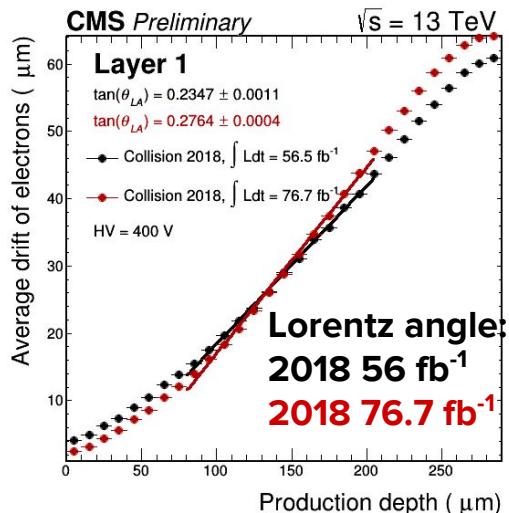
Thresholds:

Endcaps: $1500 e^-$

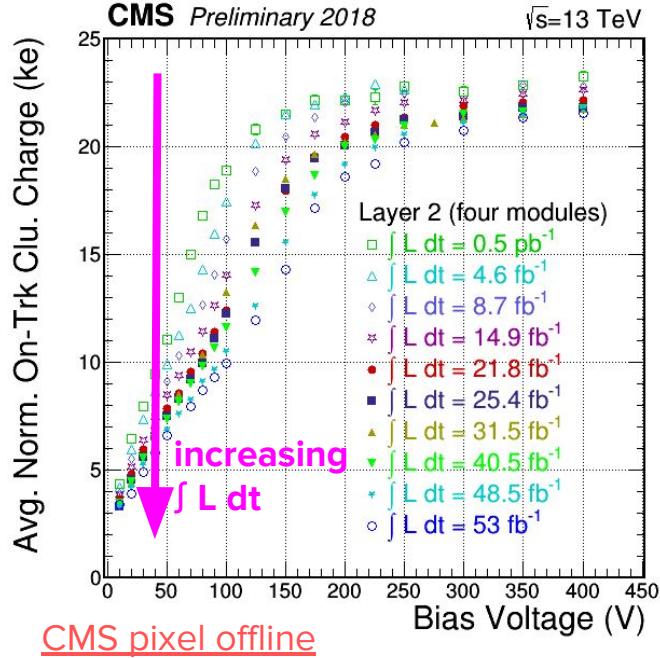
L2-4 $1200e^-$

L1: $2100e^-$

Relatively constant over time

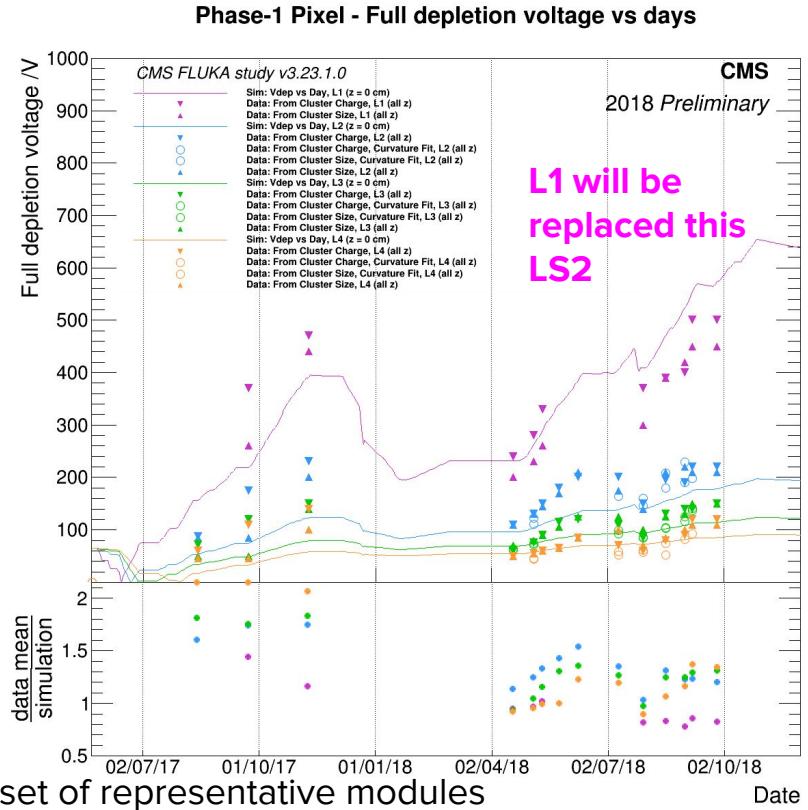


Radiation effects on depletion voltage



Regular sensor bias voltage scans on subset of representative modules

Simulation with effective space charge Hamburg model ($E_{\text{eff}}=1.21 \text{ eV}$), fluence from DPMJet + FLUKA 3.23.1.0

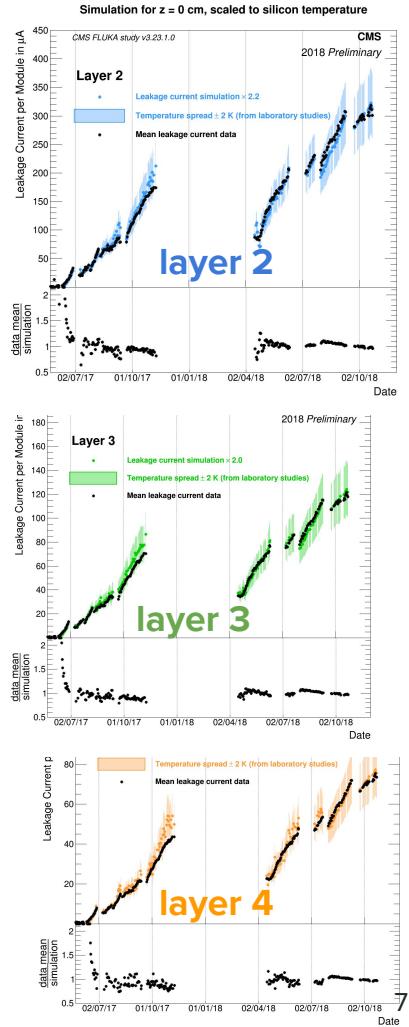
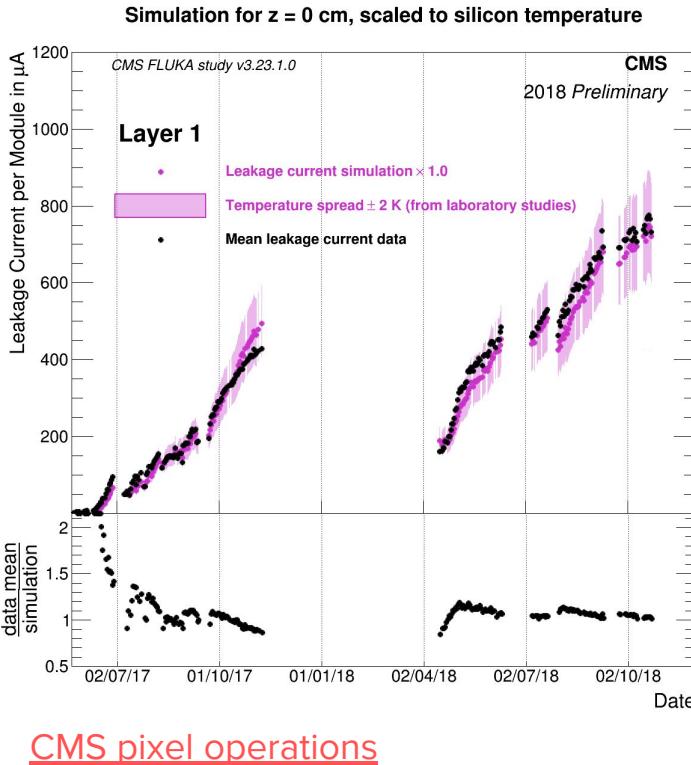


Run 3 depletion voltages expected to be within power supply limit of 800V.

Operational voltages at end of run 2:
L1: 450V
L2: 300V
L3-L4: 250V
Ring 1: 350V
Ring 2: 300V

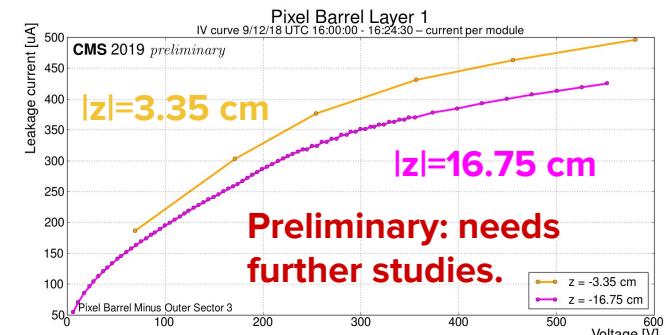
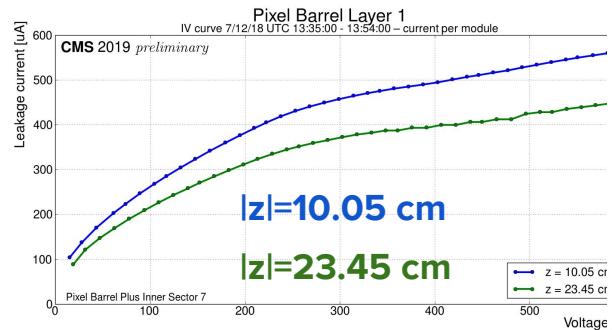
Leakage currents

- Leakage currents in L2-4 underestimated by about a factor of 2
- Main uncertainties from temperature modeling and particle generator + FLUKA
→ work on improvements in modeling foreseen
- Prediction for run 3: safely below the operational limit of the power supplies of 20mA.

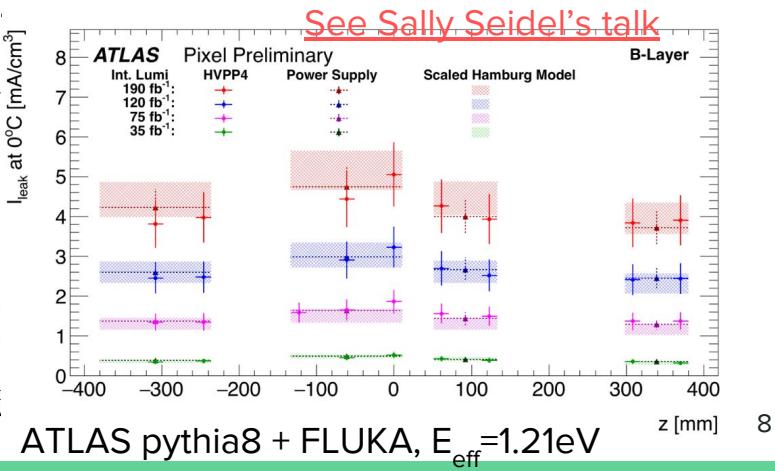
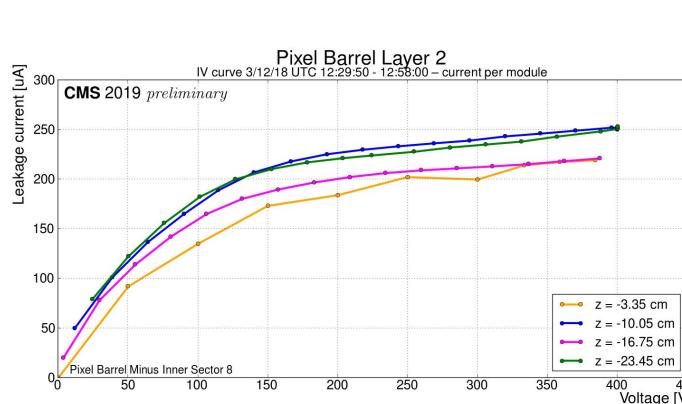


Leakage currents vs z

Leakage current
seems consistently
higher for lower z.
ATLAS sees a similar
effect.



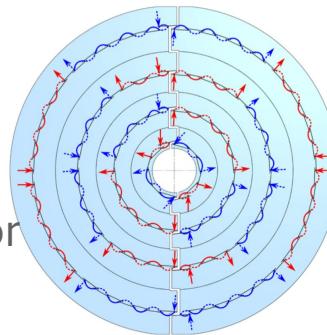
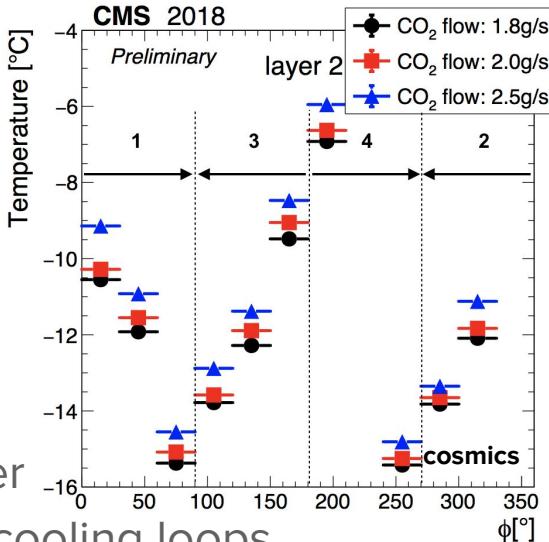
No effect seen
on layers other
than innermost:



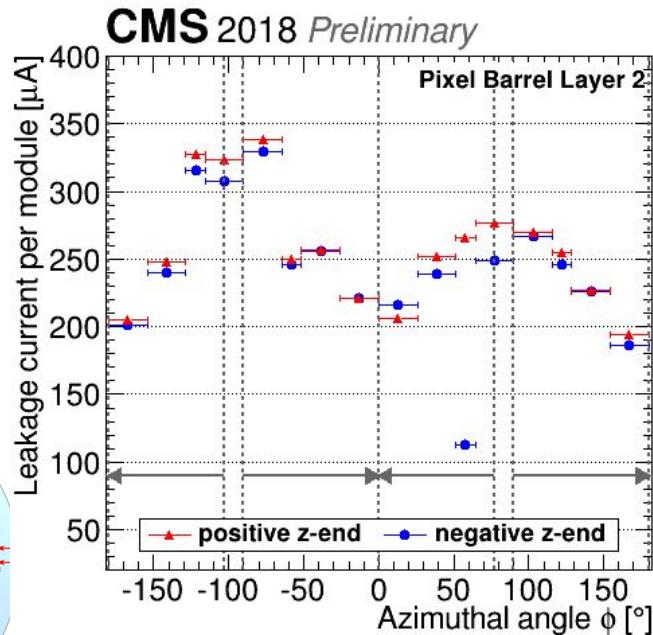
CO_2 cooling

Important to understand detector temperatures for radiation effects:

- ✓ -22°C, option to go lower
- ✓ 1.7mm Ø stainless steel cooling loops
- ✓ wall thickness 50 μm
- ✓ very lightweight
- ✗ gradient of 4-5K along cooling loop
- ✗ efficient cooling but **no efficient heating** which can be problematic for targeted **annealing or safety**

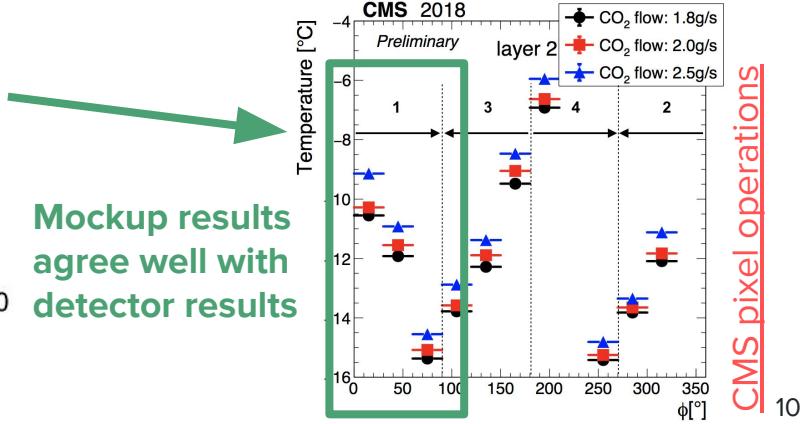
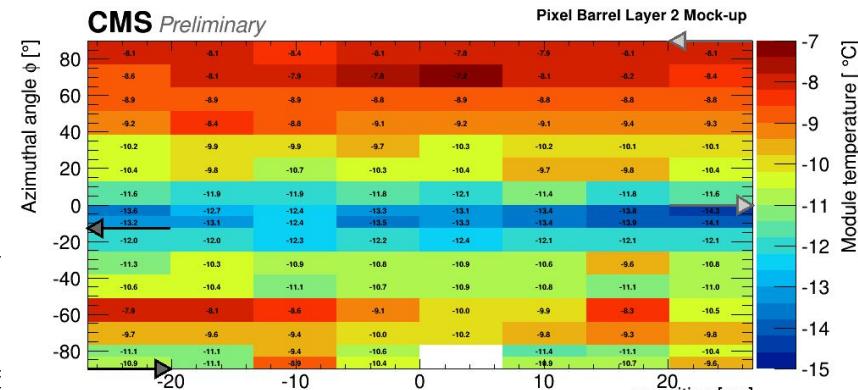
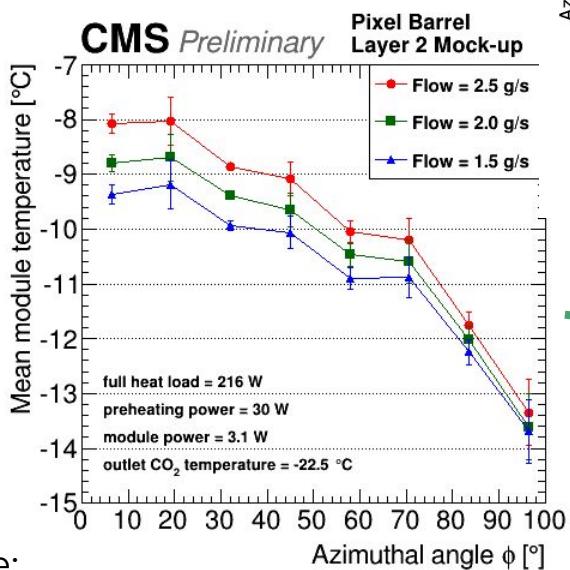


Increasing the flow did decrease some gradient but still a **non-negligible pressure drop** along cooling loop: under investigation



Temperature studies with a mockup of layer 2

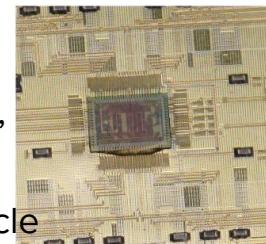
Realistic layer 2
half-shell mechanics
and CO₂ cooling with
adjustable heat load
on pseudo-modules
with temperature
sensors



Thermal mockup indispensable:

- temperature modeling is a large uncertainty for simulation
- few temperature sensors in the detector

Radiation effects in electronics



TBM

- ☐ 30/fb⁻¹ in L1 transistor in TBM flipflop sets TBM to 'no readout' mode: "**stuck TBMs**"
- ☐ recovery only with power cycle

Power supplies

PSU

1 3-4

DCDC converters

1-4

1 PSU → 3-4 DCDC converter pairs
1 DCDC converter pair → 1-4 modules



CCU misbehavior:

- ☐ 1/300pb⁻¹ reset portcard → reprogram
- ☐ 1/month reset DCDCs

From Klaas Padeken

Front end controllers/drivers

tkFEC

pxFEC

FED

command and control unit

optical links signal delays

pixel module

SEUs
token-bit manager

readout chip

readout chip

SEUs

From Benedikt Vormwald

Compensation for chip radiation effects in offline reconstruction

Irradiated DCDCs stop functioning in disabled state (not an SEU)

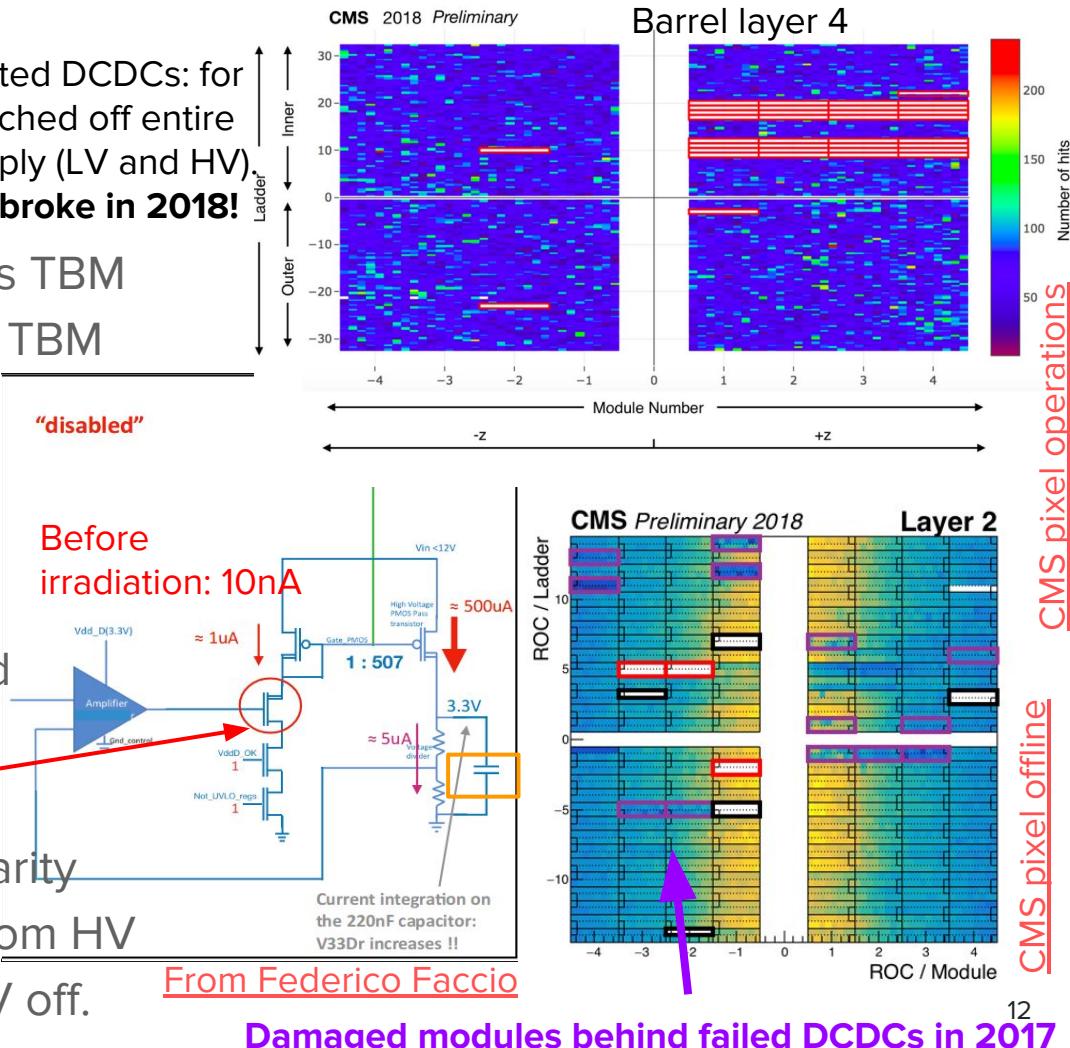
- ☐ 63/1216 at end of 2017 stopped functioning
- ☐ 333/1216 in 2017 found to have high current

ROC: solved by reprogramming

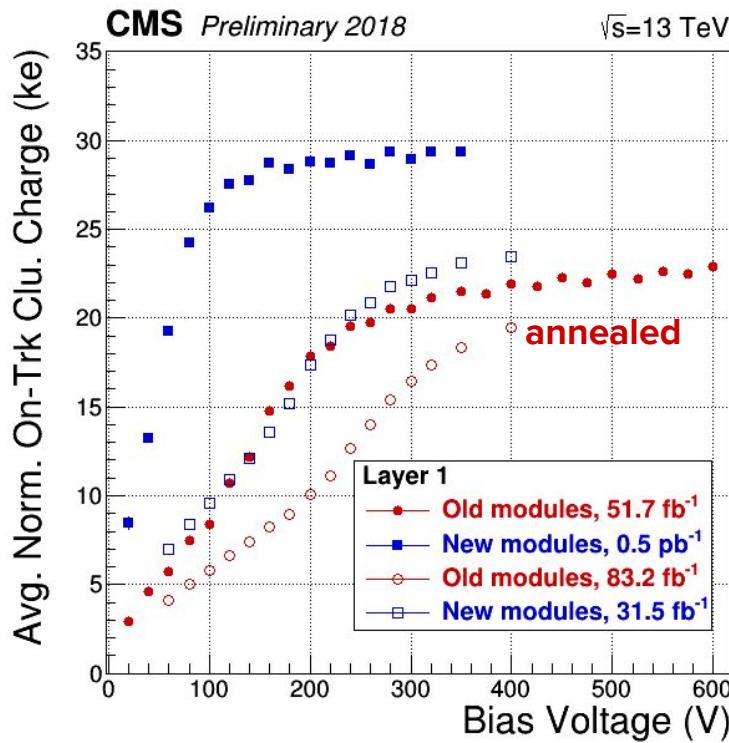
DCDCs

- SEU in transistor in TBM flipflop sets TBM to ‘no readout’ mode → powercycle TBM
- Powercycled with DCDCs (lowest amount of modules) in 2017
- Increased leakage current in DCDCs after irradiation causes charging up of **capacitor** in disabled state ← design mistake in layout around one transistor:
- High and low voltage group granularity not the same: damaged modules from HV on where DCDCs were broken → LV off.

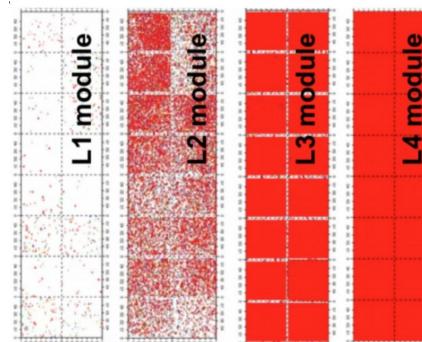
Disconnected DCDCs: for safety switched off entire power supply (LV and HV).
No DCDC broke in 2018!



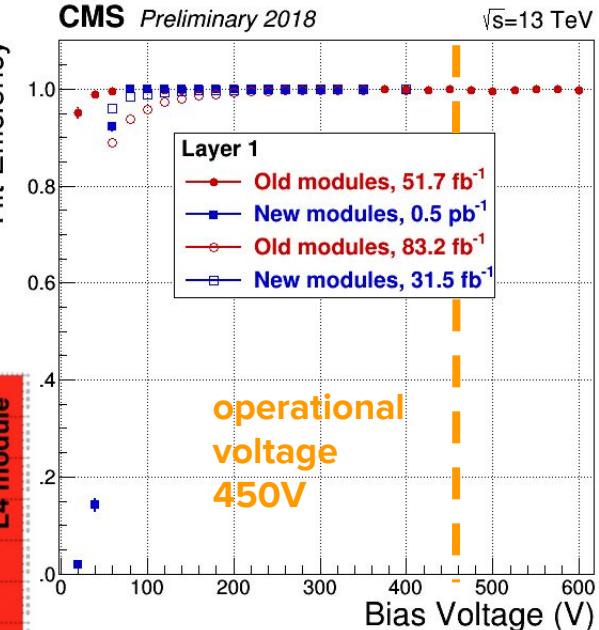
Radiation effects: on-track cluster charge



In long shutdown
2017-2018: replaced
6 of 8 layer 1
modules damaged
by high voltage
leakage current



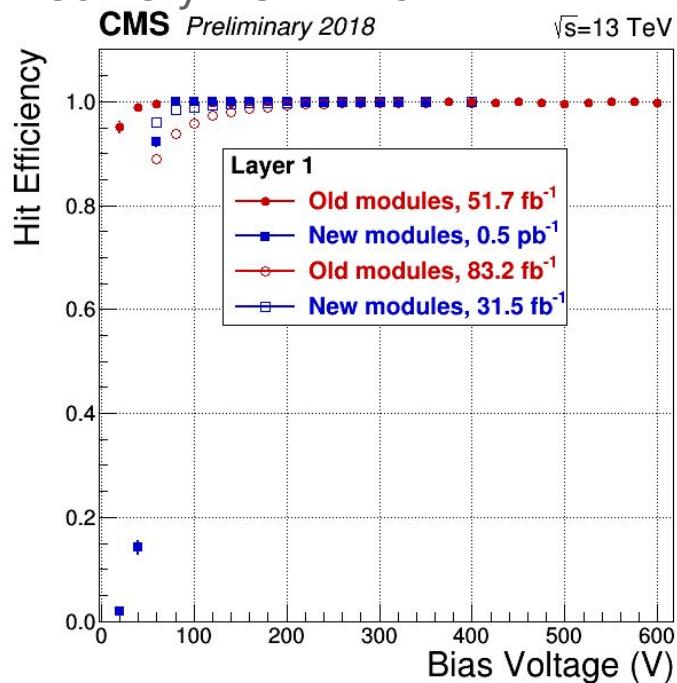
No impact on hit efficiency!



CMS pixel offline

Summary and lessons learned

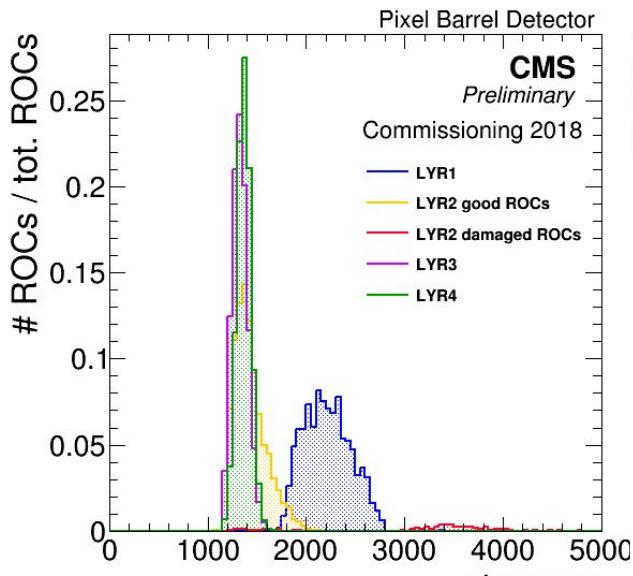
- Successful commissioning of CMS pixel detector since start of 2017
- Despite many challenges, pixel detector performed very well in 2017 and 2018
- Good to have test setups to study:
 - CO₂ cooling with adjustable heat load for understanding
 - module temperatures
 - radiation effects
- HV and LV granularity: Ideally the same
- Monitoring temperatures, chip properties important for studying radiation effects



Spares

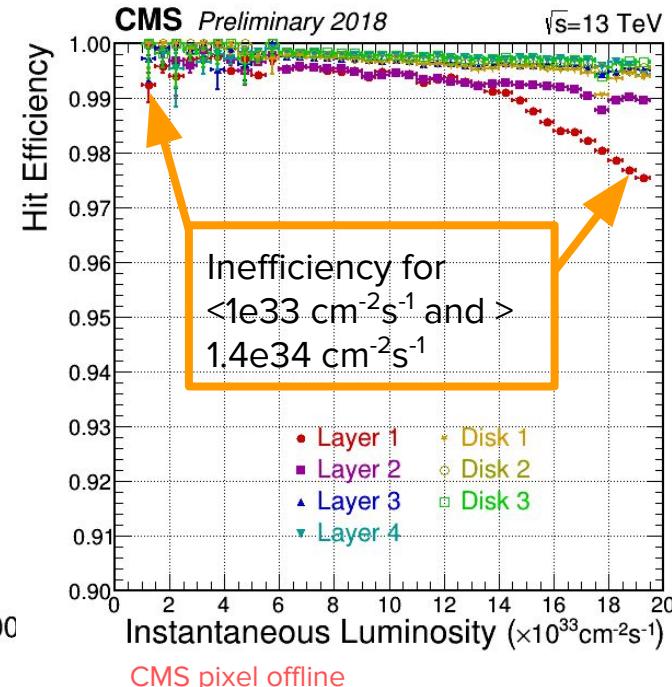
Inner layer chip: crosstalk, inefficiency, timing

- Layer 1 timing very different from layer 2
- High thresholds resulting from crosstalk and large timewalk
- Inefficiency at high and low rates
- Distribution of pedestals in analog pulse height large, ~80 ADC units

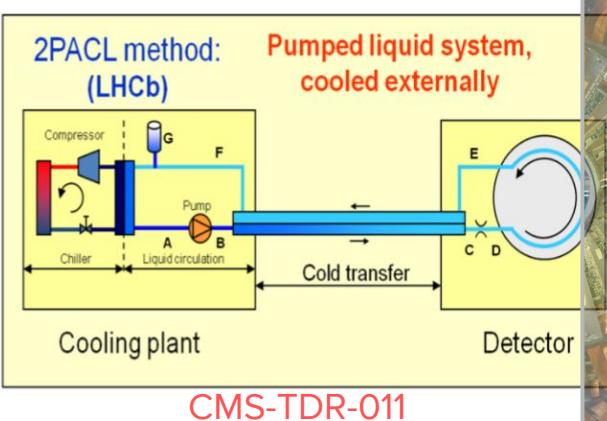


CMS pixel operations

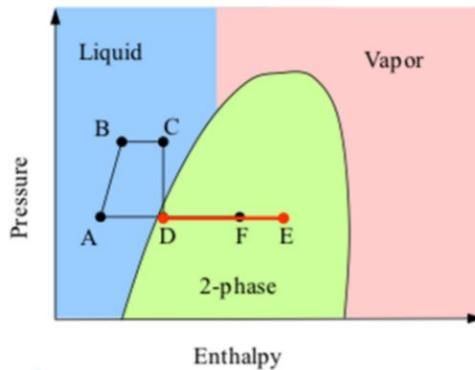
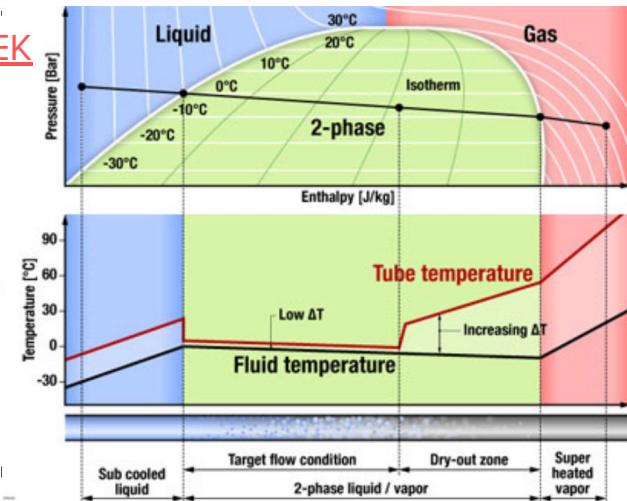
All solved/addressed in next L1 chip version.



CO_2 cooling

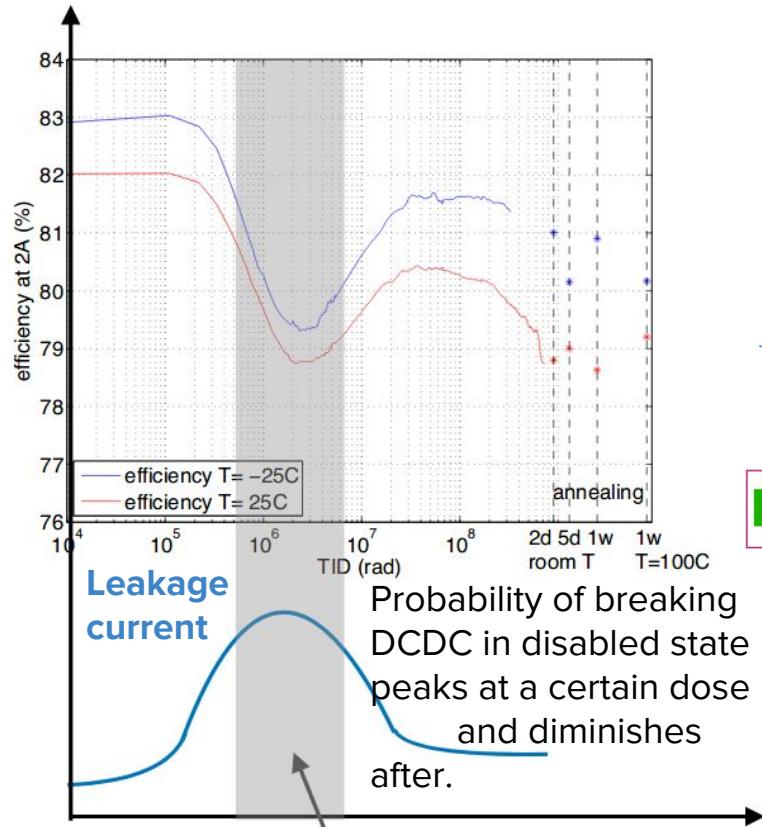


From KEK

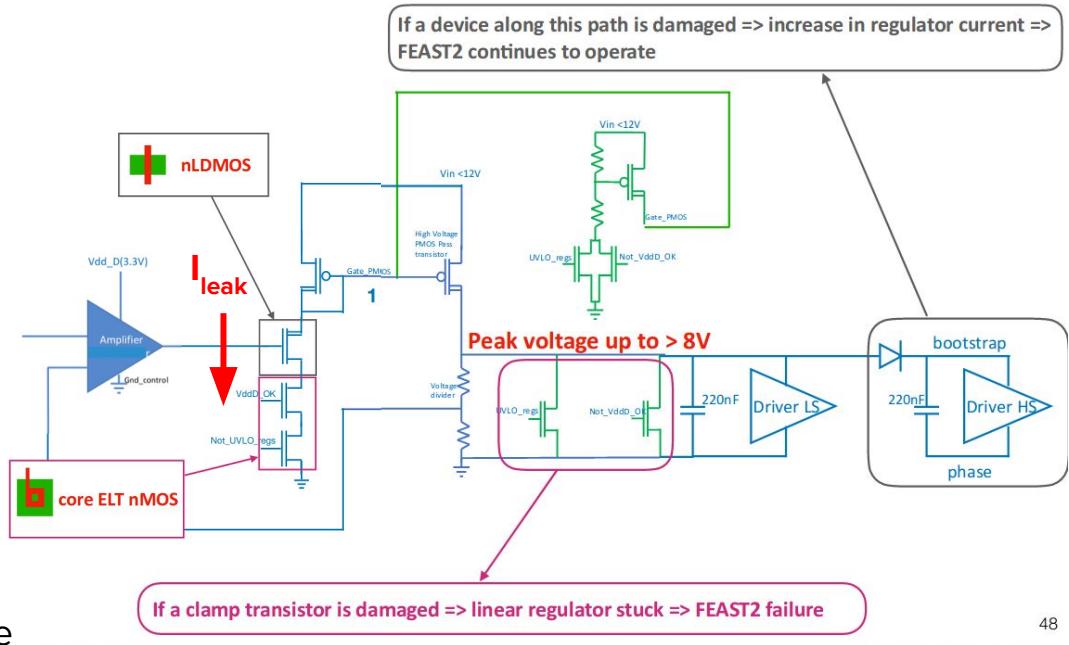


- A→B: CO_2 pressure is increased for transfer to the experiment
- B→C: temperature increases from heat exchange with returning CO_2
- C→D: pressure inside the detector is reduced to reach onset of evaporation
- D→E: heat from the detector is absorbed
- E→F: CO_2 liquid/vapor mixture condenses on incoming colder CO_2 pipe
- F→G: CO_2 is cooled with main chiller
- G: temperature in detector is regulated with pressure in accumulator:
D-G low impedance system with ~constant pressure back to D

DCDC malfunctioning

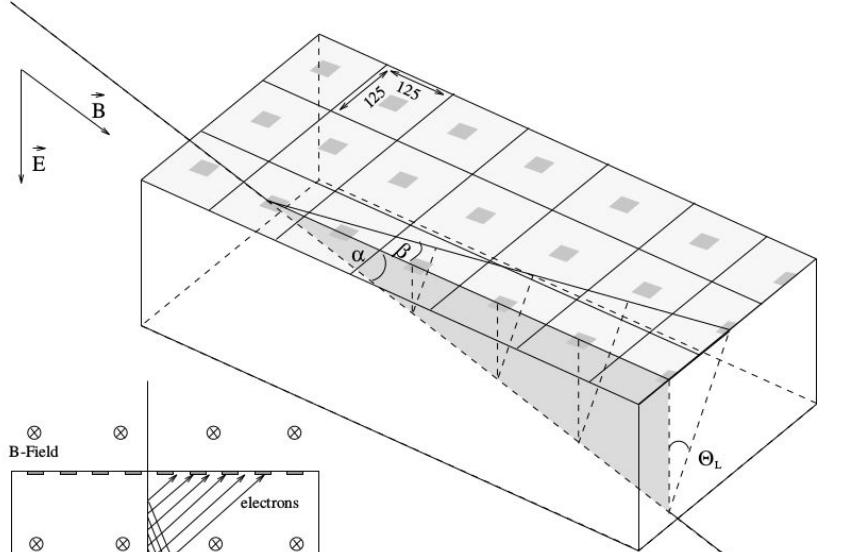


Enclosed layout (ELT) vs linear transistors → can ‘cut’ leakage current path by adding ELT in series



Capacitor charges up in disabled state and causes spikes beyond 3.3V

Cluster charge vs depth: grazing angle method



α = grazing angle
 β = mean arrival position
(mean surface charge deflection)
 Θ_L = $\arctan(\tan(\beta)/\tan(\alpha))$ = Lorentz angle

Drift direction of electrons and holes from different depths

From Henrich and Kaufmann

- Ionizing particles arriving at shallow angle create pixel “signal street”
- Each pixel in the street has a charge from part of the track → from a certain depth segment
- Compute drift and depth from track and pixel position and α , β
- Project 3D histogram of drift, depth, and charge along drift path to obtain charge vs depth.